uClamp1211P µClamp™ 1-Line ESD protection

PROTECTION PRODUCTS - MicroClamp™

Description

The $\mu Clamp^{TM}$ series of TVS arrays are designed to protect sensitive electronics from damage or latch-up due to ESD. It is designed to replace multilayer varistors (MLVs) in portable applications. It features large cross-sectional area junctions for conducting high transient currents. It offers superior electrical characteristics such as lower clamping voltage and no device degradation when compared to MLVs. They offer desirable characteristics for board level protection including fast response time, low operating and clamping voltage, and no device degradation.

The $\mu\text{Clamp}^{\text{TM}}1211\text{P}$ is in a 2-pin, RoHS/WEEE compliant, SLP1006P2 package. It measures 1.0 x 0.6 x 0.5mm. The leads are spaced at a pitch of 0.65mm and are finished with lead-free NiPdAu. Each device will protect one bidirectional line operating at ± 12 volts. It gives the designer the flexibility to protect single lines in applications where arrays are not practical. They may be used to meet the ESD immunity requirements of IEC 61000-4-2, Level 4 (± 15 kV air, ± 8 kV contact discharge). The combination of small size and high ESD surge capability makes them ideal for use in portable applications such as cellular phones, digital cameras, and MP3 players.

Features

- ◆ Transient protection for data lines to IEC 61000-4-2 (ESD) ±15kV (air), ±8kV (contact) IEC 61000-4-4 (EFT) 40A (tp = 5/50ns) Cable Discharge Event (CDE)
- ◆ Ultra-small package (1.0 x 0.6 x 0.5mm)
- Protects one I/O or power line
- Low clamping voltage
- Working voltage: ±12V
- Low leakage current
- Solid-state silicon-avalanche technology

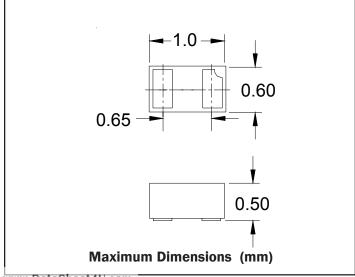
Mechanical Characteristics

- ◆ SLP1006P2 package
- Molding compound flammability rating: UL 94V-0
- Marking : Marking code
- Packaging : Tape and Reel
- Lead Finish: NiPdAu
- ◆ RoHS/WEEE Compliant

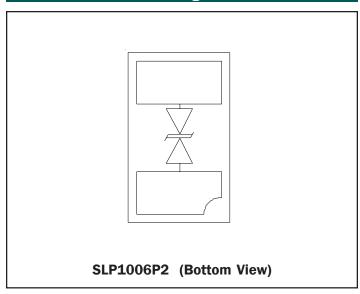
Applications

- Cellular Handsets & Accessories
- Cordless Phones
- Personal Digital Assistants (PDAs)
- Notebooks & Handhelds
- Portable Instrumentation
- Digital Cameras
- Peripherals
- MP3 Players

Dimensions



Schematic & PIN Configuration





Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power (tp = 8/20μs)	P_{pk}	200	Watts
Peak Pulse Current (tp = 8/20µs)	I _{pp}	7	Amps
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V _{ESD}	±15 ±8	kV
Operating Temperature	T _J	-55 to +125	°C
Storage Temperature	T _{STG}	-55 to +150	°C

Electrical Characteristics (T=25°C)

Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V _{RWM}				12	V
Reverse Breakdown Voltage	V_{BR}	I _t = 1mA	13.3			V
Reverse Leakage Current	I _R	V _{RWM} = 12V, T=25°C			1	μΑ
Clamping Voltage	V _c	$I_{pp} = 1A, t_p = 8/20 \mu s$			19	V
Clamping Voltage	V _c	$I_{pp} = 7A, t_p = 8/20 \mu s$			28.5	V
Junction Capacitance	C _j	V _R = OV, f = 1MHz			25	pF



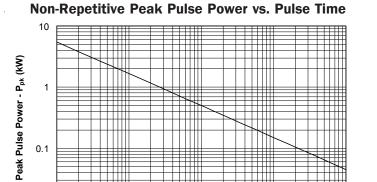
1

PROTECTION PRODUCTS

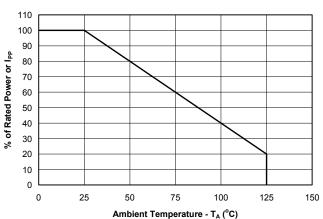
Typical Characteristics

0.01

0.1



Power Derating Curve



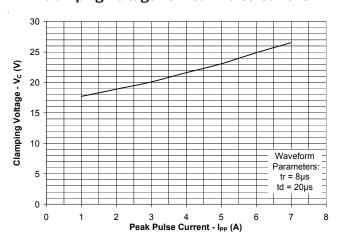
Clamping Voltage vs. Peak Pulse Current

10

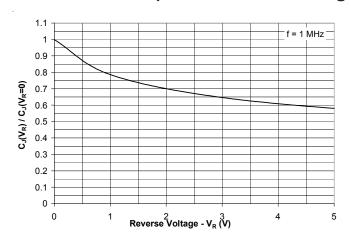
Pulse Duration - tp (µs)

100

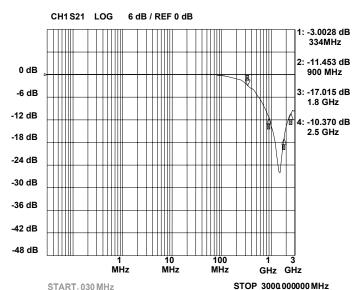
1000



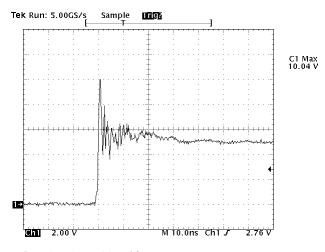
Normalized Junction Capacitance vs. Reverse Voltage



Insertion Loss (S21)



ESD Clamping (8kV Contact per IEC 61000-4-2)



Note: Data is taken with a 10x attenuator



Applications Information

Device Connection Options

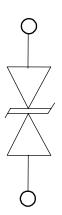
This TVS diode is designed to protect one data, I/O, or power supply line. The device is bidirectional and may be used on lines where the signal polarity can go above and below ground. The device is symmetrical, and therefore, the orientation of the device is not critical.

Circuit Board Layout Recommendations for Suppression of ESD.

Good circuit board layout is critical for the suppression of ESD induced transients. The following guidelines are recommended:

- Place the TVS near the input terminals or connectors to restrict transient coupling.
- Minimize the path length between the TVS and the protected line.
- Minimize all conductive loops including power and ground loops.
- The ESD transient return path to ground should be kept as short as possible.
- Never run critical signals near board edges.
- Use ground planes whenever possible.

Circuit Diagram





Applications Information - Spice Model

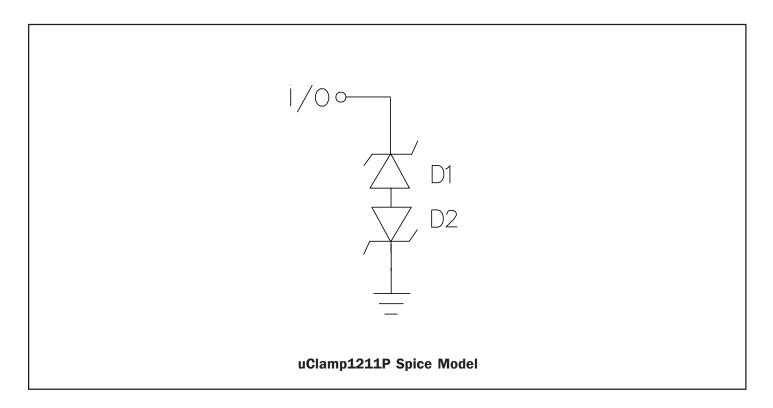
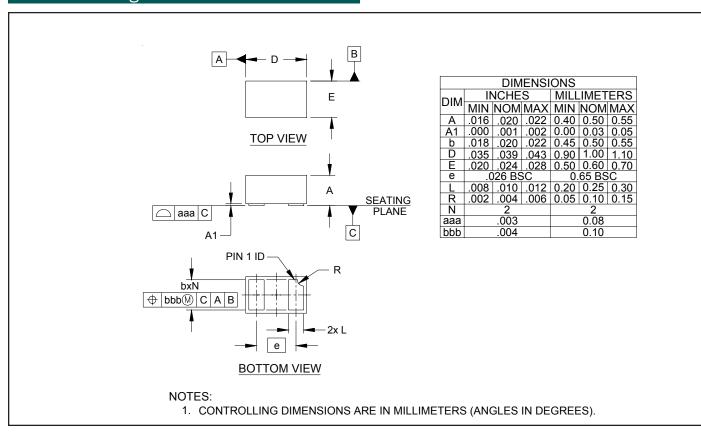


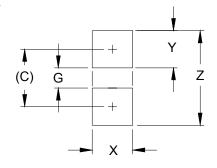
Table 1 - μClamp1211P Spice Parameters							
Parameter	Unit	D1 (TVS)	D2 (TVS)				
IS	Amp	1.48E-14	1.48E-14				
BV	Volt	15.5	15.5				
٧J	VJ Volt		0.7				
RS	Ohm	0.721	0.721				
IBV	Amp	1E-3	1E-3				
C1O	Farad	10E-12	10E-12				
TT	sec	2.541E-9	2.541E-9				
М		0.201	0.201				
N		1.1	1.1				
EG	eV	1.11 1.13					



Outline Drawing - SLP1006P2



Land Pattern - SLP1006P2



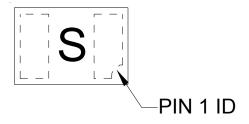
	DIMENSIONS						
DIM	INCHES	MILLIMETERS					
С	(.033)	(0.85)					
G	.012	0.30					
Х	.024	0.60					
Y	.022	0.55					
Z	.055	1.40					

NOTES:

- 1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
- 2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.



Marking Code

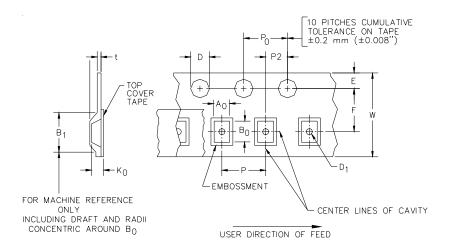


Ordering Information

Part Number	Working	Device	Qty per	Reel	
	Voltage	Marking	Reel	Size	
uClamp1211P.TCT	12V	S	3,000	7 Inch	

MicroClamp, uClamp and μClamp are marks of Semtech Corporation

Tape and Reel Specification



AO	В0	ко		
0.69 +/-0.10 mm	1.19 +/-0.10 mm	0.66 +/-0.10 mm		

Tape Width	B, (Max)	D	D1	E	F	Р	PO	P2	Т	W
8 mm	4.2 mm (.165)	1.5 + 0.1 mm - 0.0 mm (0.59 +.005 000)	0.4 mm ±0.25 (.031)	1.750±.10 mm (.069±.004)	3.5±0.05 mm (.138±.002)	4.0±0.10 mm (.157±.00- 4)	4.0±0.1 mm (.157±.00- 4)	2.0±0.05 mm (.079±.002)	0.254±0.02 mm (.016)	8.0 mm + 0.3 mm - 0.1 mm (.312±.012)

Contact Information

Semtech Corporation Protection Products Division 200 Flynn Rd., Camarillo, CA 93012 Phone: (805)498-2111 FAX (805)498-3804